

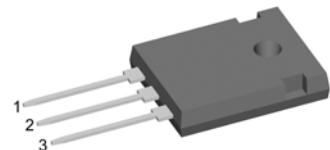
XPT IGBT

V_{CES} = 1200V
 I_{C25} = 58A
 $V_{CE(sat)}$ = 1.8V

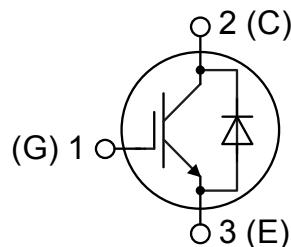
Copack

Part number

IXA33IF1200HB



Backside: collector



Features / Advantages:

- Easy paralleling due to the positive temperature coefficient of the on-state voltage
- Rugged XPT design (Xtreme light Punch Through) results in:
 - short circuit rated for 10 μ sec.
 - very low gate charge
 - low EMI
 - square RBSOA @ 3x I_c
- Thin wafer technology combined with the XPT design results in a competitive low $V_{CE(sat)}$
- SONIC™ diode
 - fast and soft reverse recovery
 - low operating forward voltage

Applications:

- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers
- Pumps, Fans

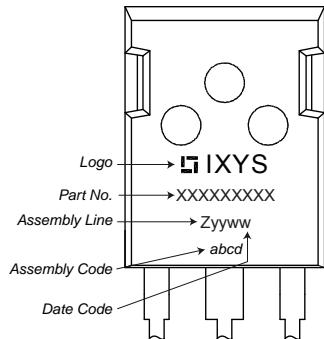
Package: TO-247

- Industry standard outline
- RoHS compliant
- Epoxy meets UL 94V-0

IGBT			Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$			1200	V	
V_{GES}	max. DC gate voltage				± 20	V	
V_{GEM}	max. transient gate emitter voltage				± 30	V	
I_{C25}	collector current	$T_c = 25^\circ C$			58	A	
I_{C80}		$T_c = 80^\circ C$			34	A	
P_{tot}	total power dissipation	$T_c = 25^\circ C$			250	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_c = 25 A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$	1.8	2.1	V	
			$T_{VJ} = 125^\circ C$	2.1		V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_c = 1 mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	5.4	5.9	6.5	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$		0.1	mA	
			$T_{VJ} = 125^\circ C$	0.1		mA	
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			500	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_c = 25 A$		76		nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600 V; I_c = 25 A$ $V_{GE} = \pm 15 V; R_G = 39 \Omega$		70		ns	
t_r	current rise time			40		ns	
$t_{d(off)}$	turn-off delay time			250		ns	
t_f	current fall time			100		ns	
E_{on}	turn-on energy per pulse			2.5		mJ	
E_{off}	turn-off energy per pulse			3		mJ	
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 39 \Omega$	$T_{VJ} = 125^\circ C$				
I_{CM}		$V_{CEmax} = 1200 V$			75	A	
SCSOA	short circuit safe operating area	$V_{CEmax} = 900 V$					
t_{sc}	short circuit duration	$V_{CE} = 900 V; V_{GE} = \pm 15 V$	$T_{VJ} = 125^\circ C$		10	μs	
I_{sc}	short circuit current	$R_G = 39 \Omega$; non-repetitive		100		A	
R_{thJC}	thermal resistance junction to case				0.5	K/W	
R_{thCH}	thermal resistance case to heatsink			0.25		K/W	
Diode							
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$			1200	V	
I_{F25}	forward current	$T_c = 25^\circ C$			60	A	
I_{F80}		$T_c = 80^\circ C$			33	A	
V_F	forward voltage	$I_F = 30 A$	$T_{VJ} = 25^\circ C$		2.20	V	
			$T_{VJ} = 125^\circ C$	1.95		V	
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$		*	mA	
	* not applicable, see I_{CES} value above		$T_{VJ} = 125^\circ C$	*		mA	
Q_{rr}	reverse recovery charge	$V_R = 600 V$ $-di_F/dt = -600 A/\mu s$ $I_F = 30 A; V_{GE} = 0 V$		3.5		μC	
I_{RM}	max. reverse recovery current			30		A	
t_{rr}	reverse recovery time			350		ns	
E_{rec}	reverse recovery energy			0.9		mJ	
R_{thJC}	thermal resistance junction to case				0.7	K/W	
R_{thCH}	thermal resistance case to heatsink			0.25		K/W	

Package TO-247			Ratings		
Symbol	Definition	Conditions	min.	typ.	max.
		per terminal			Unit
I_{RMS}	<i>RMS current</i>			70	A
T_{VJ}	<i>virtual junction temperature</i>		-40		150 °C
T_{op}	<i>operation temperature</i>		-40		125 °C
T_{stg}	<i>storage temperature</i>		-40		150 °C
Weight				6	g
M_D	<i>mounting torque</i>		0.8		1.2 Nm
F_c	<i>mounting force with clip</i>		20		120 N

Product Marking

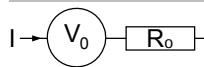


Part number

I = IGBT
 X = XPT IGBT
 A = Gen 1 / std
 33 = Current Rating [A]
 IF = Copack
 1200 = Reverse Voltage [V]
 HB = TO-247AD (3)

Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	IXA33IF1200HB	IXA33IF1200HB	Tube	30	508562

Equivalent Circuits for Simulation

** on die level* $T_{VJ} = 150^\circ\text{C}$ 

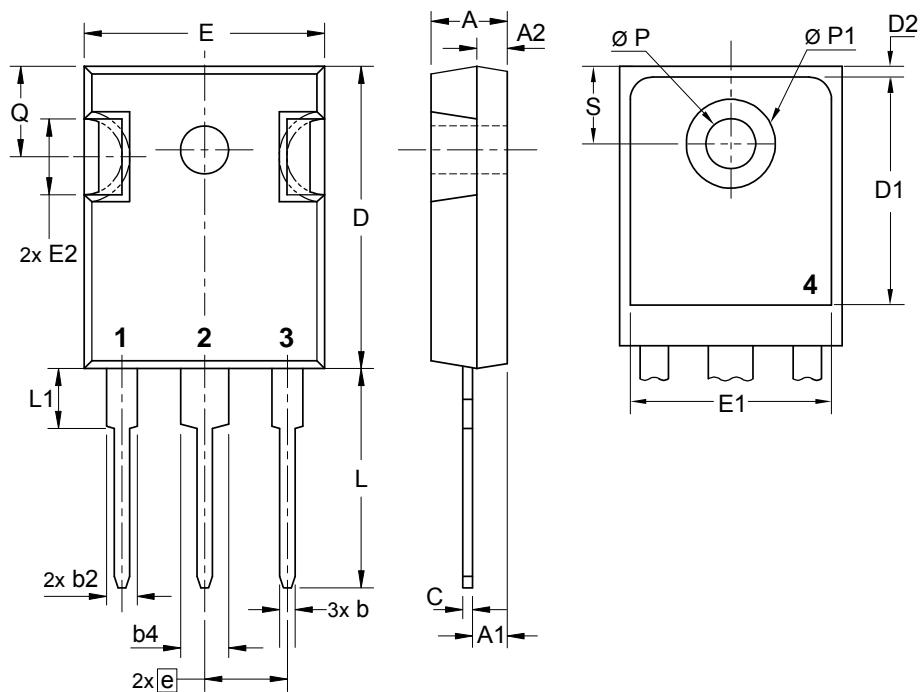
IGBT

Diode

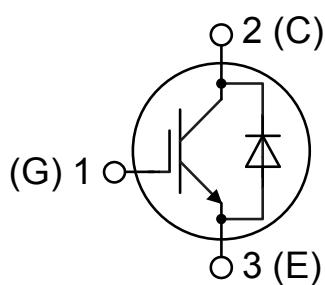
$V_{0\max}$ threshold voltage
 $R_{0\max}$ slope resistance *

1.1	1.25	V
55	28.3	mΩ

Outlines TO-247



Sym.	Inches min. max.	Millimeter min. max.
A	0.185 0.209	4.70 5.30
A1	0.087 0.102	2.21 2.59
A2	0.059 0.098	1.50 2.49
D	0.819 0.845	20.79 21.45
E	0.610 0.640	15.48 16.24
E2	0.170 0.216	4.31 5.48
e	0.215 BSC	5.46 BSC
L	0.780 0.800	19.80 20.30
L1	- 0.177	- 4.49
Ø P	0.140 0.144	3.55 3.65
Q	0.212 0.244	5.38 6.19
S	0.242 BSC	6.14 BSC
b	0.039 0.055	0.99 1.40
b2	0.065 0.094	1.65 2.39
b4	0.102 0.135	2.59 3.43
c	0.015 0.035	0.38 0.89
D1	0.515 -	13.07 -
D2	0.020 0.053	0.51 1.35
E1	0.530 -	13.45 -
Ø P1	- 0.29	- 7.39



IGBT

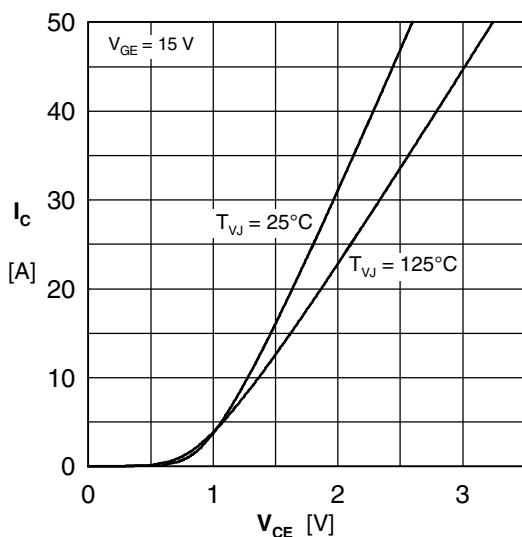


Fig. 1 Typ. output characteristics

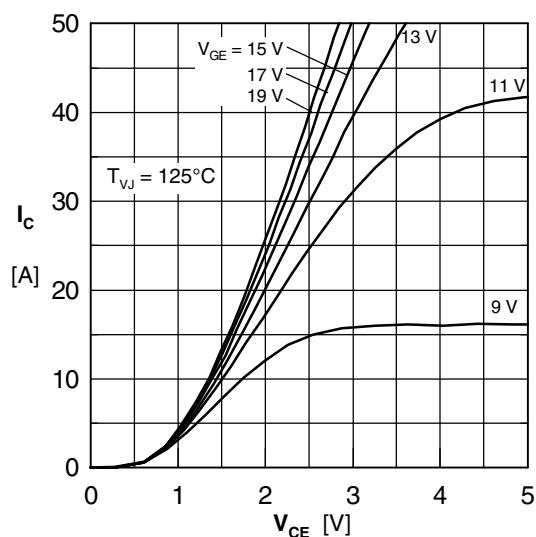


Fig. 2 Typ. output characteristics

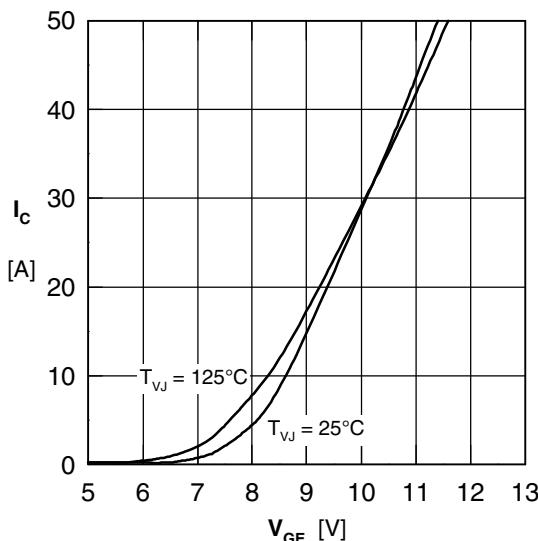


Fig. 3 Typ. transfer characteristics

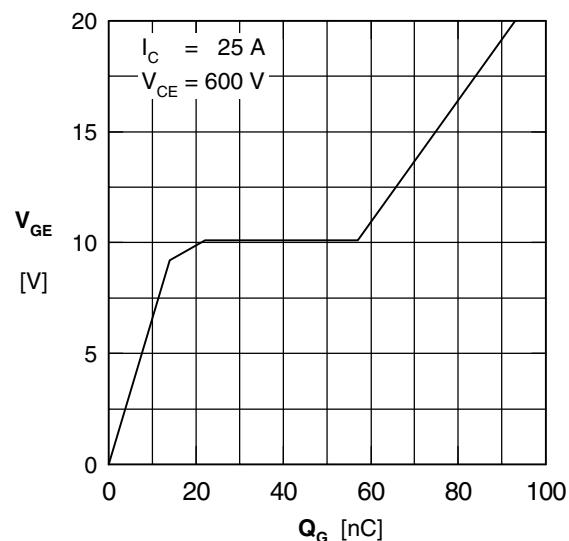


Fig. 4 Typ. turn-on gate charge

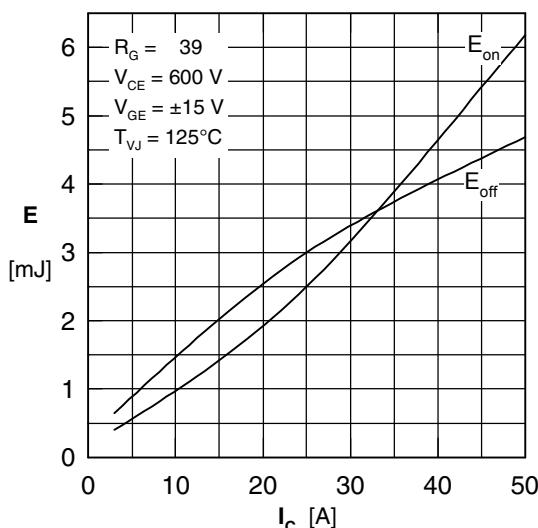


Fig. 5 Typ. switching energy vs. collector current

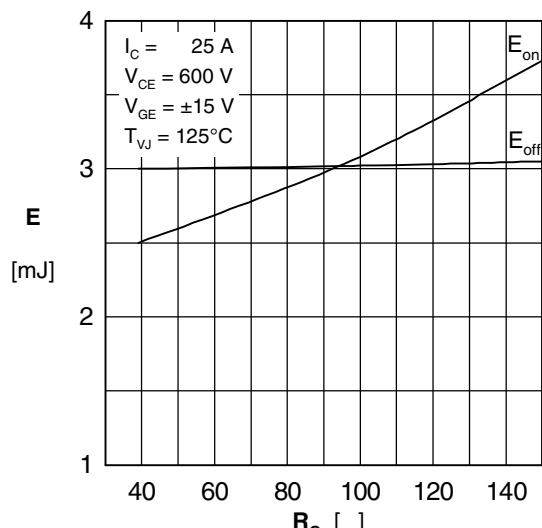
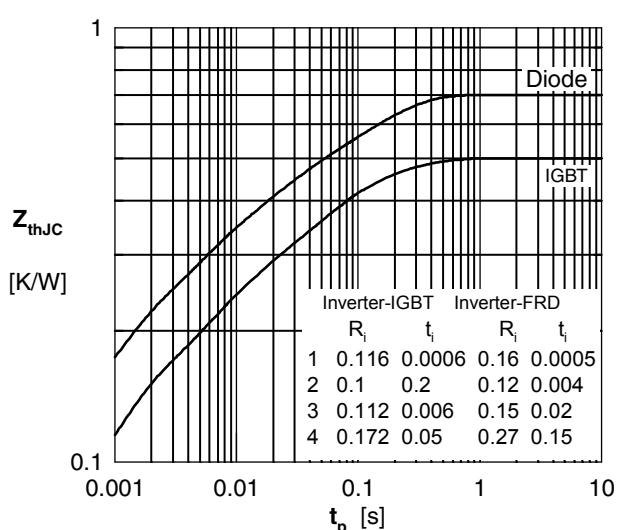
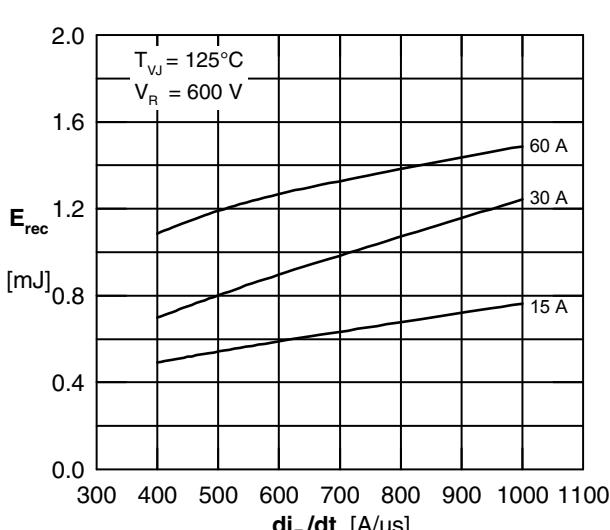
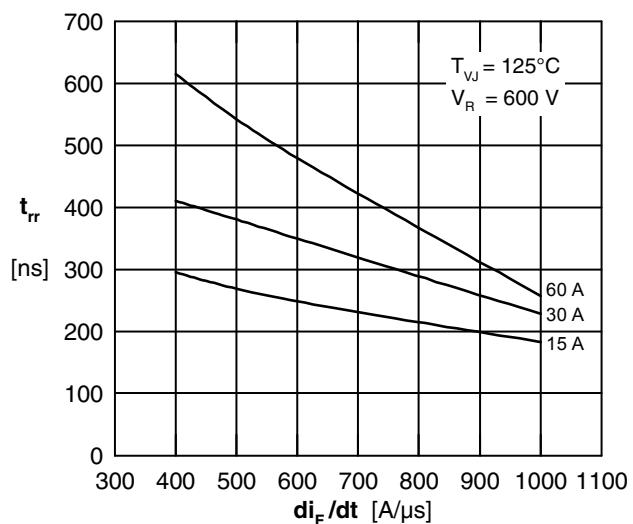
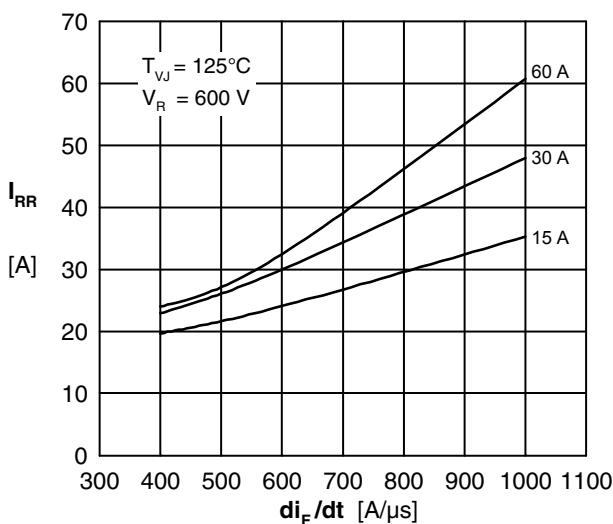
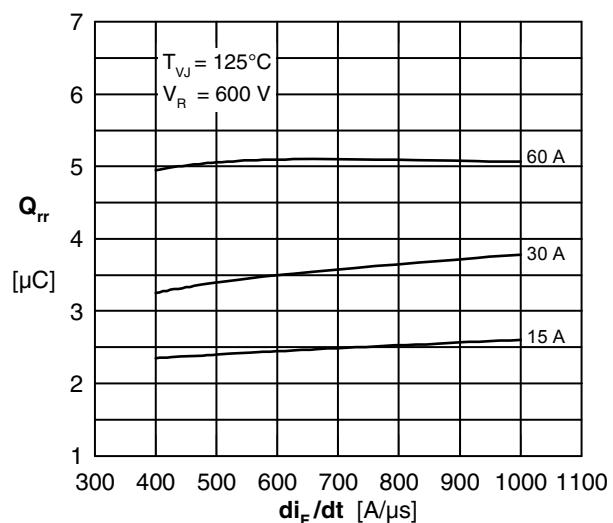
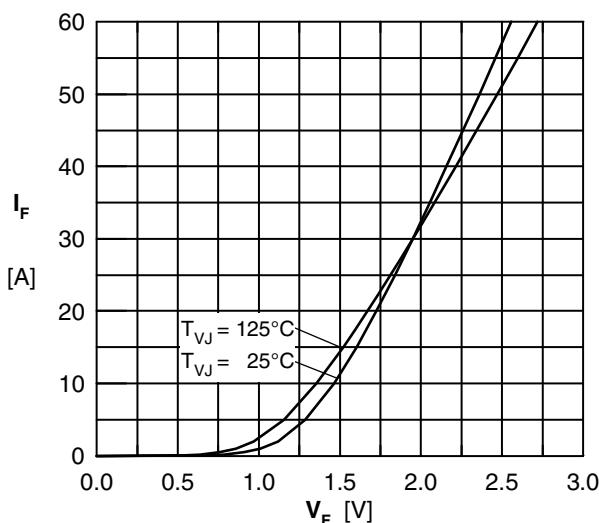


Fig. 6 Typ. switching energy vs. gate resistance

Diode





Disclaimer Notice - Information furnished is believed to be accurate and reliable. However, users should independently evaluate the suitability of and test each product selected for their own applications. Littelfuse products are not designed for, and may not be used in, all applications. Read complete Disclaimer Notice at www.littelfuse.com/disclaimer-electronics.